Docket No.: 61282-055 PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re Application of

Customer Number: 20277

Takeshi KOBAYASHI, et al.

Confirmation Number: 4950

Serial No.: 10/757,388

Group Art Unit: 2812

Filed: January 15, 2004

Examiner: To be Assigned

For: LEAD FRAME, METHOD OF MANUFACTURING THE SAME, SEMICONDUCTOR

DEVICE USING LEAD FRAME AND METHOD OF MANUFACTURING

SEMICONDUCTOR DEVICE

REQUEST FOR CORRECTED FILING RECEIPT

Mail Stop Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Attached is a copy of the Filing Receipt received from the U.S. Patent and Trademark Office in the above-referenced application. It is noted that the residence information of the second inventor is incorrect. Attached is a copy of the Declaration and Power of Attorney Document, which evidences that the second Inventor information should read: **Hisao Sugoh**, **Tochigi**, **JAPAN**. It is requested that a corrected filing receipt be issued.

Respectfully submitted,

MCDERMOTT, WILL & EMERY

Michael E. Fogarty Registration No. 36,139

600 13th Street, N.W. Washington, DC 20005-3096 (202) 756-8000 MEF:mcw Facsimile: (202) 756-8087

Date: May 18, 2004



UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Offices
Address: COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, Viginia 22313-1450
www.usplu.gov

DRAWINGS TOT CLMS

01/15/2004

FILING OR 371

(c) DATE

ART UNIT

FIL FEE REC'D 1054

ATTY.DOCKET NO

IND CLMS 4

10/757,388

APPL NO.

2812

61282-055

11

31

CONFIRMATION NO. 4950

McDERMOTT, WILL & EMERY 600 13th Street, N.W. Washington, DC 20005-3096

FILING RECEIPT *OC000000012389309*

Date Mailed: 04/19/2004

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Takeshi Kobayashi, Tochigi, JAPAN; Hisao Sugoh, Tochigi, JP, JAPAN;

Assignment For Published Patent Application

Matsushita Electric Industrial Co., Ltd.;

Domestic Priority data as claimed by applicant

Foreign Applications

JAPAN P.2003-008349 01/16/2003

If Required, Foreign Filing License Granted: 04/19/2004

Projected Publication Date: 07/29/2004

Non-Publication Request: No

Early Publication Request: No

Title

Lead frame, method of manufacturing the same, semiconductor device using lead frame and method of manufacturing semiconductor device

LICENSE FOR FOREIGN FILING UNDER Title 35, United States Code, Section 184 Title 37, Code of Federal Regulations, 5.11 & 5.15

GRANTED

The applicant has been granted a license under 35 U.S.C. 184, if the phrase "IF REQUIRED, FOREIGN FILING LICENSE GRANTED" followed by a date appears on this form. Such licenses are issued in all applications where the conditions for issuance of a license have been met, regardless of whether or not a license may be required as set forth in 37 CFR 5.15. The scope and limitations of this license are set forth in 37 CFR 5.15(a) unless an earlier license has been issued under 37 CFR 5.15(b). The license is subject to revocation upon written notification. The date indicated is the effective date of the license, unless an earlier license of similar scope has been granted under 37 CFR 5.13 or 5.14.

This license is to be retained by the licensee and may be used at any time on or after the effective date thereof unless it is revoked. This license is automatically transferred to any related applications(s) filed under 37 CFR 1.53(d). This license is not retroactive.

The grant of a license does not in any way lessen the responsibility of a licensee for the security of the subject matter as imposed by any Government contract or the provisions of existing laws relating to espionage and the national security or the export of technical data. Licensees should apprise themselves of current regulations especially with respect to certain countries, of other agencies, particularly the Office of Defense Trade Controls, Department of State (with respect to Arms, Munitions and Implements of War (22 CFR 121-128)); the Office of Export Administration, Department of Commerce (15 CFR 370.10 (j)); the Office of Foreign Assets Control, Department of Treasury (31 CFR Parts 500+) and the Department of Energy.

NOT GRANTED

No license under 35 U.S.C. 184 has been granted at this time, if the phrase "IF REQUIRED, FOREIGN FILING LICENSE GRANTED" DOES NOT appear on this form. Applicant may still petition for a license under 37 CFR 5.12, if a license is desired before the expiration of 6 months from the filing date of the application. If 6 months has lapsed from the filing date of this application and the licensee has not received any indication of a secrecy order under 35 U.S.C. 181, the licensee may foreign file the application pursuant to 37 CFR 5.15(b).



DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that: My residence, post office and citizenship are as stated below next to my name, · I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter claimed and for which a patent is sought on the invention entitled LEAD FRAME, METHOD OF MANUFACTURING THE SAME, SEMICONDUCTOR DEVICE USING LEAD FRAME AND METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, the specification of which X is attached hereto. was filed on as Application Serial No. was amended on (if applicable). I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose information which is known to me to be material to patentability in accordance with Title 37, Code of Federal Regulations, Section 1.56. I hereby claim foreign priority benefits under Title 35, United States Code, Section 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed: **Prior Foreign Applications(s): Priority Claimed** Number Country Day/Month/Year filed P. 2003-008349 Japan 16/January/2003 I hereby claim the benefit under 35 USC §119(e) of any United States provisional application(s) listed below. **Prior Provisional Application(s): Application Number** Filing Date I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application: **Prior U.S. Application(s):** Serial No. Status: Patented, Pending, Abandoned Filing Date

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the following attorney(s) and/or agent(s): Stephen A. Becker, Reg. No. 26,527; John G. Bisbikis, Reg. No. 37,095; Christopher D. Bright, Reg. No. 46,578; Daniel Bucca, Reg. No. 42,368; Kenneth L. Cage, Reg. No. 26,151; Stephen C. Carlson, Reg. No. 39,929; Jennifer Chen, Reg. No. 42,404; Bernard P. Codd, Reg. No. 46,429; Thomas A. Corrado, Reg. No. 42,439; Lawerence T. Cullen, Reg. No. 44,489; Paul Devinsky, Reg. No. 28,553; Margaret M. Duncan, Reg. No. 30,879; Ramyar M. Farid, Reg. No. 46,692; Brian E. Ferguson, Reg. No. 36,801; Michael E. Fogarty, Reg. No. 36,139; John R. Fuisz, Reg. No. 37,327; Willem F. Gadiano, Reg. No. 37,136; Keith E. George, Reg. No. 34,111; Matthew V. Grumbling, Reg. No. 44,427; John A. Hankins, Reg. No. 32,029; Joseph Hyosuk Kim, Reg. No. 41,425; Eric J. Kraus, Reg. No. 36,190; Catherine Krupka, Reg. No. 46,227; Jack Q. Lever, Reg. No. 28,149; Raphael V. Lupo, Reg. No. 28,363; Michael A. Messina, Reg. No. 33,424; Dawn L. Palmer, Reg. No. 41,238; Joseph H. Paquin, Jr., Reg. No. 31,647; Scott D. Paul, Reg. No. 42,984; William D. Pegg, Reg. No. 42,988; Robert L. Price, Reg. No. 22,685; Thomas D. Robbins, Reg. No. 43,669; Gene Z. Rubinson, Reg. No. 33,351; Joy Ann G. Serauskas, Reg. No. 27,952; Daniel H. Sherr, Reg. No. 46,425; David A. Spenard, Reg. No. 37,449; Arthur J. Steiner, Reg. No. 26,106; David L. Stewart, Reg. No. 37,578; Wesley Strickland, Reg. No. 44,363; Michael D. Switzer, Reg. No. 39,552; Leonid D. Thenor, Reg. No. 39,397; Daniel S. Trainor, Reg. No. 43,959; Weiffenbach, Reg. No. 44,488; Aaron Weisstuch, Reg. No. 41,557; Edward J. Wise, Reg. No. 34,523; Alexander V. Yampolsky, Reg. No. 36,324; and Robert W. Zelnick, Reg. No. 36,976 all of

McDERMOTT, WILL & EMERY 600 13th Street, N.W. Washington, DC 20005-3096

Direct Telephone Calls to:

Telephone 202-756-8000

with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith, and all future correspondence should be addressed to them.

Full name of sole or first inventor: Takeshi Kobayashi	
Inventor's signature: Takeshi 20 bayashi	Date: January 7, 2004
Residence: Tochigi, Japan	
Citizenship: Japan -	
Post Office Address: 232-18, Uwano-machi, Kanuma-shi, Tochigi 322-00	021 Japan

<u>-</u>	
second Full name of Hirkinventor: Hisao Sugoh	
Inventor's signature: Misac Sugoh	Date: January 7, 2004
Residence: Tochigi, Japan	·
Citizenship: Japan	
Post Office Address: 492, Nishimizunuma, Haga-machi, Haga-gun, Tochigi 321-3324 Japan	
Full name of second inventor:	
Inventor's signature:	Date:
Residence:	
Citizenship: Japan	
Post Office Address:	
	Date:
Full name of fifth inventor:	
Inventor's signature:	Date:
Residence:	
Citizenship:	
Post Office Address:	
Full name of sixth inventor:	
Inventor's signature:	Date:
Residence:	
Citizenship:	
Post Office Address:	
Full name of seventh inventor:	
Inventor's signature:	Date:
Residence:	
Citizenship:	
Post Office Address:	